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NCE2304

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE2304 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge .This device is suitable for use as a load switch or in PWM applications.

General Features

• $V_{DS} = 30V, I_D = 3.6A$

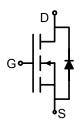
 $R_{DS(ON)}$ < 73m Ω @ V_{GS} =4.5V

 $R_{DS(ON)}$ <58m Ω @ V_{GS} =10V

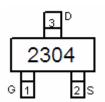
- High power and current handing capability
- Lead free product is acquired
- Surface mount package

Application

- Battery protection
- Load switch
- Power management



Schematic diagram



Marking and pin assignment



SOT-23 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
2304	NCE2304	SOT-23	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	3.6	Α
Drain Current-Pulsed (Note 1)	I _{DM}	15	Α
Maximum Power Dissipation	P _D	1.7	W
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ hetaJA}$	73.5	°C/W

Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30	33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μΑ



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Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=250\mu A$	1.2	1.5	2.2	V
Drain-Source On-State Resistance	D	V _{GS} =4.5V, I _D =3.1A	-	58	73	mΩ
	R _{DS(ON)}	V_{GS} =10V, I_{D} =3.6A	-	40	58	mΩ
Forward Transconductance	g fs	V_{DS} =5 V , I_D =3.6 A	-	11	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	V _{DS} =15V,V _{GS} =0V,	-	230	ı	PF
Output Capacitance	Coss	F=1.0MHz	-	40	ı	PF
Reverse Transfer Capacitance	C _{rss}	F = 1.0WH12	-	17	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	10	-	nS
Turn-on Rise Time	t _r	V _{DD} =10V,I _D =3.6A	-	50	-	nS
Turn-Off Delay Time	$t_{d(off)}$	V_{GS} =4.5 V , R_{GEN} =6 Ω	-	10	-	nS
Turn-Off Fall Time	t _f		-	20	ı	nS
Total Gate Charge	Q_g	\/ -15\/ -2.64	-	4.0	-	nC
Gate-Source Charge	Q_{gs}	V_{DS} =15V, I_{D} =3.6A, V_{GS} =10V	-	0.75	-	nC
Gate-Drain Charge	Q_{gd}	VGS-10V	-	0.65	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =2.7A	-	8.0	1.2	V
Diode Forward Current (Note 2)	Is		-	-	1.6	Α

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

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Typical Electrical and Thermal Characteristics

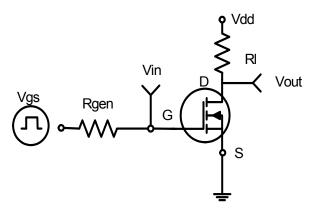
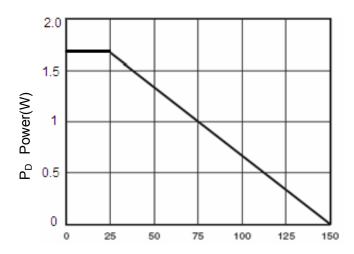
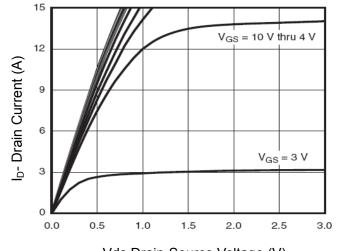


Figure 1:Switching Test Circuit



T_J-Junction Temperature(°C)

Figure 3 Power Dissipation



Vds Drain-Source Voltage (V)
Figure 5 Output Characteristics

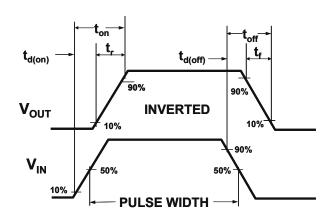


Figure 2:Switching Waveforms

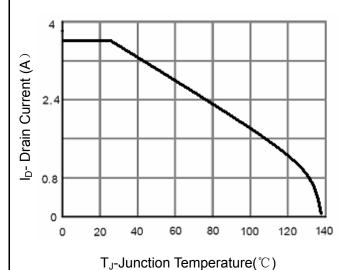


Figure 4 Drain Current

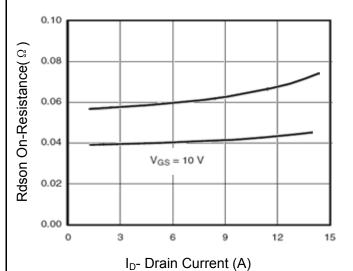
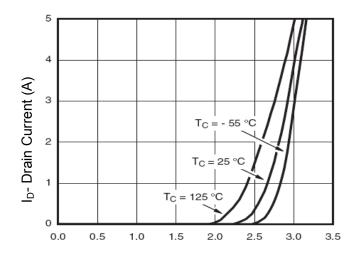


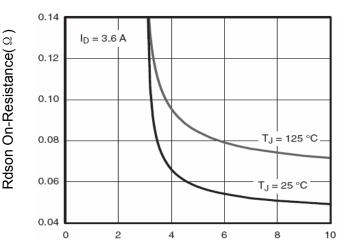
Figure 6 Drain-Source On-Resistance





Vgs Gate-Source Voltage (V)

Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V)

Figure 9 Rdson vs Vgs

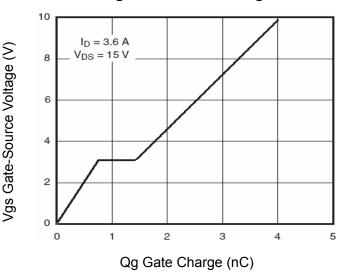
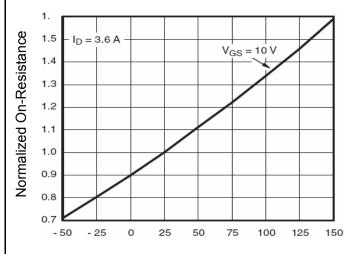
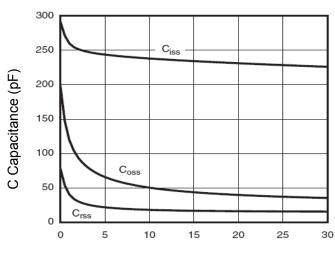


Figure 11 Gate Charge



 T_J -Junction Temperature($^{\circ}$ C)

Figure 8 Drain-Source On-Resistance



Vds Drain-Source Voltage (V)

Figure 10 Capacitance vs Vds

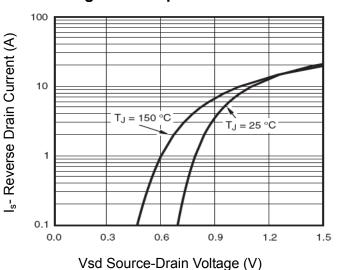
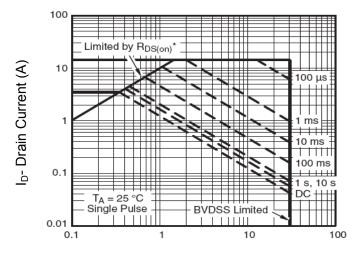


Figure 12 Source- Drain Diode Forward





Vds Drain-Source Voltage (V)

Figure 13 Safe Operation Area

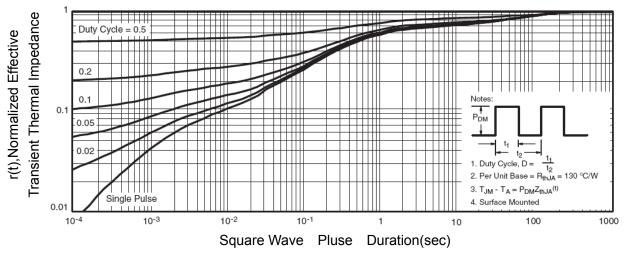
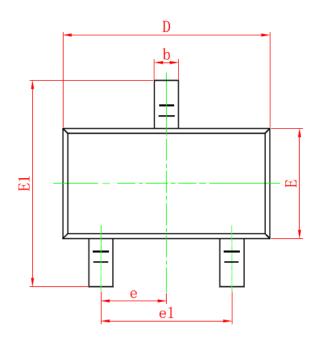
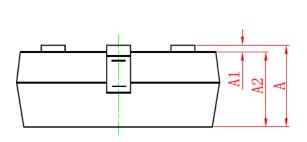


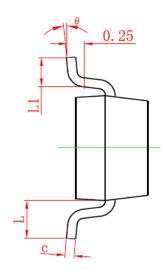
Figure 14 Normalized Maximum Transient Thermal Impedance



SOT-23 Package Information







Symbol	Dimensions in Millimeters			
	MIN.	MAX.		
Α	0.900	1.150		
A 1	0.000	0.100		
A2	0.900	1.050		
b	0.300	0.500		
С	0.080	0.150		
D	2.800	3.000		
E	1.200	1.400		
E1	2.250	2.550		
е	0.950TYP			
e1	1.800	2.000		
L	0.550REF			
L1	0.300	0.500		
θ	0°	8°		

Notes

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- $5. \ Controlling \ dimension \ is \ millimeter, \ converted \ inch \ dimensions \ are \ not \ necessarily \ exact.$



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